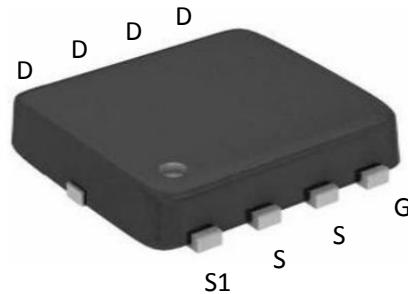


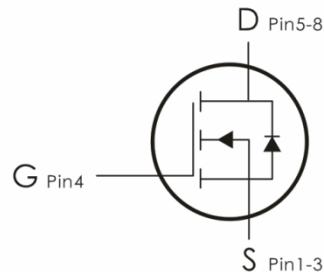
Description:

This N-Channel MOSFET uses advanced trench technology to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.



Features:

- 1) $V_{DS}=30V, I_D=40A, R_{DS(ON)}<10m\Omega @ V_{GS}=10V$
- 2) Improved dv/dt capability
- 3) Fast switching
- 4) 100% EAS Guaranteed
- 5) Green Device Available.



Absolute Maximum Ratings: ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current Continuous ($T_c=25^\circ C$)	40	A
	Continuous Drain Current- ($T_c=100^\circ C$)	24	
I_{DM}	Drain Current – Pulsed ¹	160	A
E_{AS}	Single Pulse Avalanche Energy ²	24.2	mJ
I_{AS}	Avalanche Current ²	22	A
P_D	Power Dissipation ($T_c=25^\circ C$)	31	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Thermal Characteristics:

Symbol	Parameter	Max	Units
R_{eJC}	Thermal Resistance,Junction to Case ¹	4	°C/W

R_{θJA}	Thermal Resistance,Junction to Ambient ¹	62	°C/W
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Package Marking and Ordering Information:

Part NO.	Marking	Package
ZC010NG	C010N	DFN3*3-8

Electrical Characteristics: ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\ \mu\text{A}$	30	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{GS}=0\text{V}, V_{DS}=30\text{V}, T_J=25^\circ\text{C}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{A}$	---	---	± 100	nA
On Characteristics						
V_{GS(th)}	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu\text{A}$	1	---	2.5	V
R_{DS(ON)}	Drain-Source On Resistance ³	$V_{GS}=10\text{V}, I_D=15\text{A}$	---	8.5	10	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=10\text{A}$	---	11	17	
G_{FS}	Forward Transconductance	$V_{DS}=5\text{V}, I_D=15\text{A}$	---	24.4	---	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	---	896	---	pF
C_{oss}	Output Capacitance		---	126	---	
C_{rss}	Reverse Transfer Capacitance		---	108	---	
Switching Characteristics						
t_{d(on)}	Turn-On Delay Time ^{3,4}	$V_{DD}=15\text{V}, V_{GS}=10\text{V}, R_G=3\ \Omega, I_D=10\text{A}$	---	6.4	---	ns
t_r	Rise Time ^{3,4}		---	5	---	ns
t_{d(off)}	Turn-Off Delay Time ^{3,4}		---	25	---	ns
t_f	Fall Time ^{3,4}		---	7	---	ns
Q_g	Total Gate Charge ^{3,4}		---	19	---	nC
Q_{gs}	Gate-Source Charge ^{3,4}	$V_{DS}=15\text{V}, V_{GS}=10\text{V}, I_D=20$	---	6.54	---	nC
Q_{gd}	Gate-Drain "Miller" Charge ^{3,4}		---	4.54	---	nC

Drain-Source Diode Characteristics

I_S	Contiuos Source Current	---	---	40	A
I_{SM}	Pulsed Source Current	---	---	160	A
V_{SD}	Source-Drain Diode Forward Voltage	V _{GS} =0V , I _S =40A	---	1.2	V
t_{rr}	Reverse Recovery Time	I _F =20A ,di/dt=100A/μs	---	7	nS
	Reverse Recovery Charge		---	6.3	nC

Notes:

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V,L=0.1mH,I_{AS}=22A.,R_G=25Ω,Starting T_J=25°C.
3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
4. Essentially independent of operating temperature.

Typical Characteristics: (T_C=25°C unless otherwise noted)

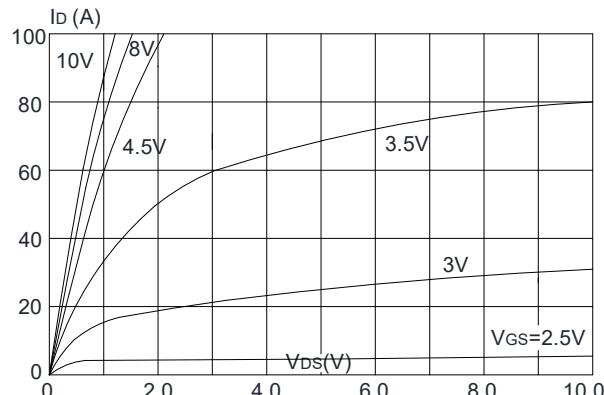


Figure 1: Output Characteristics

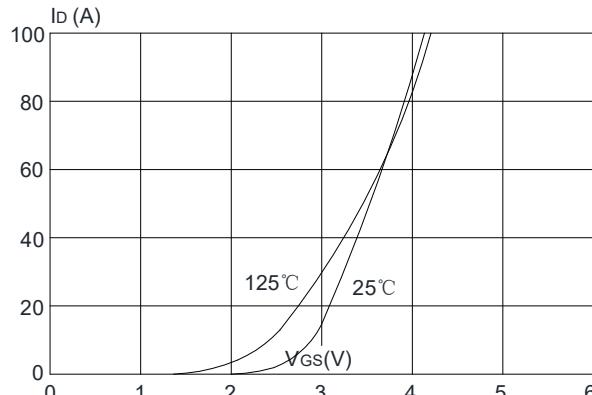


Figure 2: Typical Transfer Characteristics

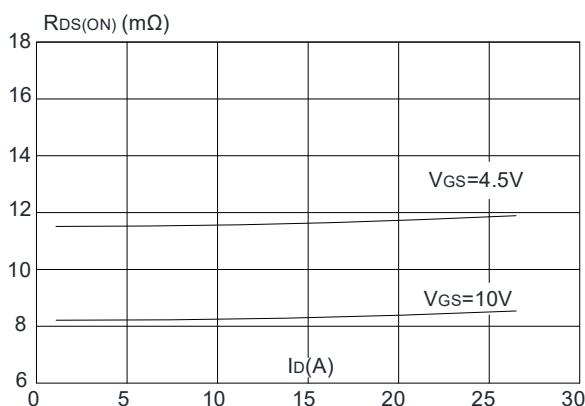


Figure 3:On-resistance vs. Drain Current

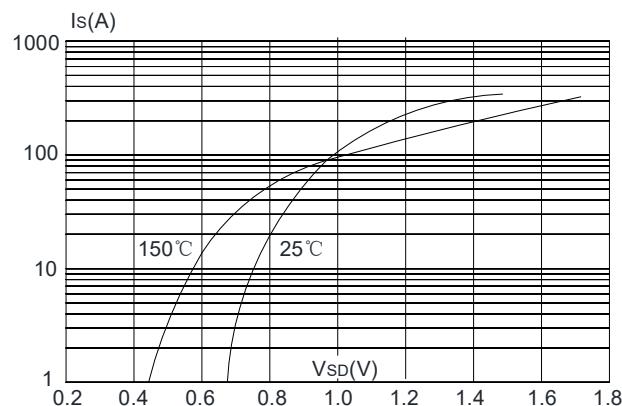


Figure 4: Body Diode Characteristics

